

Application No.: 09/990,160

Docket No.: JCLA6875

**REMARKS****Present Status of the Application**

The Office Action rejected claims 1-19. Specifically, the Office Action rejected claims 1, 5-6 and 12-14 under 35 U.S.C. 102 (b) as being anticipated by Akram et al. (U. S. Patent 5,994,166). The Office Action rejected claims 2-4 under 35 U.S.C. 103(a) as being unpatentable over Akram et al. in view of Higgins, III (U. S. Patent 6,064,114). The Office Action also rejected claims 7-11 and 15-19 under 35 U.S.C. 103(a) as being unpatentable over Akram et al.. Applicants have amended claims 1 and 12 to improve clarity. After entry of the amendments, claims 1-19 remain pending in the present application. Reconsideration of those claims is respectfully requested.

**Discussion of Claim Rejections 35 USC 102**

The Office Action rejected claims 1, 5-6 and 12-14 under 35 U.S.C. 102 (b) as being anticipated by Akram et al..

Applicant respectfully traverses the rejection.

Nevertheless, in order to improve the clarity, Applicants have amended independent claims 1 and 12.

As recited in the amended claims 1 and 12, the chip set is made of a single piece cut from a wafer. Claim 1 further specifies that "a plurality of circuits not within the substrate are located within the chip set between the chips and electrically connect the chips to each other". While claim 12 further specifies that "the chip set further includes a circuit to coupled the chips together". Akram et al fail to teach or suggest these features.

The Office Action, particularly, states the rejections in page 5 about the circuit (160, 158,

Application No.: 09/990,160

Docket No.: JCLA6875

and 154). However, it should be noted that, in Akram et al., the element 160 is a wirebond 160, the element 158 is substrate electrical traces 158, and the element 154 is a backside 154 of the dice 150. The chip 150 with the connection elements (160, 158, and 154) is disposed on another substrate 140.

The dice 150 on the substrate 140 does not equally disclose the claimed circuit, which is within the chips set as recited in the claims. In other words, the circuit ((160, 158, and 154) is not within the chip set.

Akram et al. simply do not teach or suggest a chip set of a single piece cut from a wafer and the chip set having a plurality of chips.

For at least the foregoing reasons, independent claims 1 and 12 are not anticipated by Akram et al.. For at least the same reasons, dependent claims 5-6 and 13-14 are not anticipated by Akram et al. either.

#### **Discussion of Claim Rejections 35 USC 103**

The Office action also rejected claims 2-4 under 35 U.S.C. 103(a) as being unpatentable over Akram et al. in view of Higgins, III. The Office Action rejected claims 7-11 and 15-19 under 35 U.S.C. 103(a) as being unpatentable over Akram et al.. Applicants respectfully traverse the rejections for at least the reasons set forth below.

With respect to dependent claims 2-4, 7-11, and 15-19, Akram et al. fail to disclose the foregoing missing features in independent claims 1 and 12. Higgins, III cannot not provide the missing features. Therefore, independent claims 1 and 12 are patentable over Akram and Higgins III.

For at least the same reasons, claims 2-4, 7-11, and 15-19 are also patentable over Akram

Application No.: 09/990,160

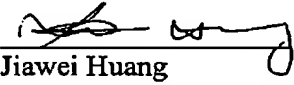
Docket No.: JCLA6875

and Higgins, III.

**CONCLUSION**

For at least the foregoing reasons, it is believed that all the pending claims 1-19 of the present application patentably define over the prior art and are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Respectfully submitted,

Date: 1/20/2004  
Jiawei Huang  
Registration No.: 43,330

J.C. Patents  
4 Venture, Suite 250  
Irvine, CA 92618  
Tel.: (949) 660-0761  
Fax : (949) 660-0809